

## Technical Data Sheet



**Product Type:** No Clean Solder Paste

**Product Name:** Microbond® PE823

**Product ID:** F823 SA35-89M30

### Description

F823 SA35-89M30 solder paste is a ready-to-use, homogeneous mixture with low odour characteristics, consisting of metal powder, binders, solvents, fluxes and thixotropic agents. The material provides a very high Surface insulation resistance of the flux residues. The solder paste is especially optimised to solder Tin-Silver-, Thin-Silver-Copper and Low-melting-alloys.

### Key Benefits

- Especially suitable for Reflow in convection and vacuum ovens.
- Exceptional print to print consistency
- Min. 8 hours tack and work life

### Compliant Products

- Flux TF 823

### Applications

- Printing

### Product Code and Alloy

Product Code					Powder Properties		
Paste	Alloy	Metal Content	*Viscosity	Powder Type	Particle Size	Alloy	Melting Point
F823	SA35	89%	M	3	25 – 45 µm	Sn96.5/Ag3.5	221 °C

\*D = Dispense grade M = Print grade H = Print grade, high L = Dipping/Jetting grade, Low

### Flux Activity

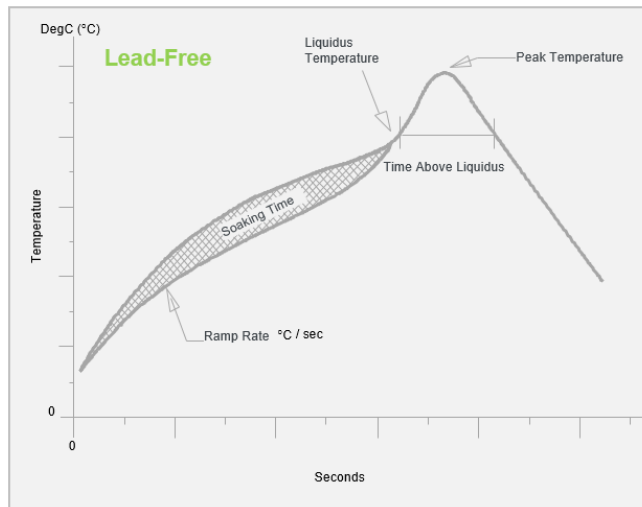
Activity Level (J-STD 004)	ISO 9454-1 {DIN EN 29454-1}	Classification
RELO	1.2.3.C	No Clean/ Solvent Clean

### Halogen Content

Halogen-Zero (No halogen added in the flux)
Tolerances: Halogen < 50 ppm; measured according to BS EN 14582

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### Recommended Reflow Profile



\* Graph not drawn to scale

Recommended Profile	
Average Ramp Rate	1 – 3 °C/s
Peak Temperature	15 °C (min) – 40 °C (max) above Melting Temperature
Time above liquidus	60 – 120 s
Reflow Atmosphere	Reflow in N <sub>2</sub> and/or Vacuum

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### Cleaning Instructions

For cleaning of wet paste or if desired for cleaning of flux residues Zestron and Vigon cleaners can be used. Flux residues have to be removed within max, 4 hours after reflow by spraying deionized water of min. 50 °C. For alternative cleaning methods– see separate cleaning recommendations.

### Storage

- Store the solder paste in tightly-sealed containers and avoid exposure to sunlight and high humidity
- Max expiration date: please refer to the expiry date on the label of the packaged product
- Storage condition in the refrigerator at 1 - 10 °C
- Store cartridges with tip pointing downwards

### Paste Preparation

- Remove paste from fridge: Before opening the package, leave paste for at least 4 hours (depending on jar/ cartridge size) at room temperature, so that paste warms up
- Do not open jar/cartridge while paste is cold to prevent condensation
- Do not heat the paste beyond room temperature
- Before using of paste jar: To obtain uniform, stable viscosity stir paste for 1 to 2 min, using a stainless steel or chemically resistive plastic spatula

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